

ABSTRACT

The application relates to a device for adjusting the gap of a die arrangement using a thermopin, which is connected to the die lip (10) without any play by means of a clamp-type socket (7), where the clamp-type socket (7) engages on the one hand in a lip nose (11) and on the other hand in a groove (5) of the thermopin (1), where the lip nose (11) is an integral part of the die lip (10) and the clamp-type socket (7) has a bore (8), and the thermopin (1) has a bore (4) and a fixing means is passed through the bores (8) and (4).